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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 1765
Examiner: Binh X. Tran
Confirmation No.: 2583

In Re PATENT APPLICATION Of:

Applicant: Yuichiro Miyamori et al.

Serial No.: 10/667,511

Filed: September 23, 2003

For: METHOD OF FORMING
DUMMY WAFER

Attny Ref.: OKI 376

) AMENDMENT

) _____
December 19, 2005Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This paper is in response to the Official Action mailed on September 19, 2005. No fee is due. However, please charge our Deposit Account No. 18-0002 if any fees are needed to enter this paper, and please advise us accordingly. It is noted that no petition is required because of the authorization to charge, but please consider this paper a petition for extension of time if needed.

The new claims are patentable for the reasons below and are supported in the specification and original claims as follows: claim 9 (1000 μm) page 6, line 3 of last paragraph; claim 10 (100 μm) page 7, lines 1 and 17; claim 11 (less than 30 μm), page 7, line 3 of last paragraph; claim 12 (substantially 670 μm), page 7, line 6 of last paragraph; claim 13 (deionized water), page 7, line 7; claim 14, page 4, lines 6-22; claim 15 (blasting is not applied to the front surface of the silicon dummy wafer), page 4, line 8 claim 16, original claim 2; claim 17, original claim 4; and claims 18-19, paragraph spanning pages 5-6.